2SB1462J

Silicon PNP epitaxial planer type

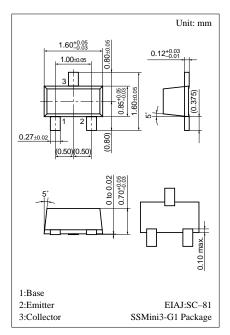
For general amplification Complementary to 2SD2216J

Features

- High foward current transfer ratio hFE.
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

| Parameter | Symbol | Ratings | Unit | | | | |
|------------------------------|------------------|------------|------|--|--|--|--|
| Collector to base voltage | V _{CBO} | -60 | V | | | | |
| Collector to emitter voltage | V _{CEO} | -50 | V | | | | |
| Emitter to base voltage | V_{EBO} | _7 | V | | | | |
| Peak collector current | I _{CP} | -200 | mA | | | | |
| Collector current | I _C | -100 | mA | | | | |
| Collector power dissipation | P _C | 125 | mW | | | | |
| Junction temperature | Tj | 125 | °C | | | | |
| Storage temperature | T _{stg} | -55 ~ +125 | °C | | | | |

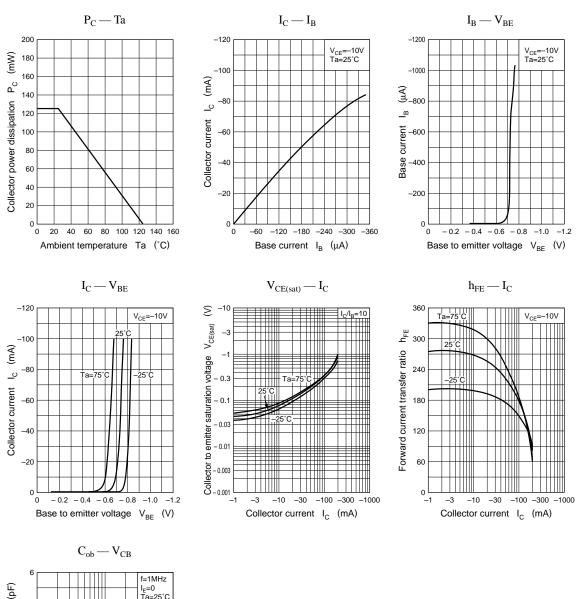
Absolute Maximum Ratings (Ta=25°C)

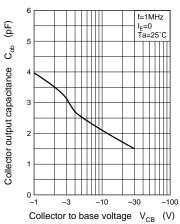


Marking symbol : A

Electrical Characteristics (Ta=25°C)

| Parameter | Symbol | Conditions | min | typ | max | Unit |
|---|----------------------|---|-----|-------|-------|------|
| Collector cutoff current | I _{CBO} | $V_{CB} = -20V, I_E = 0$ | | | - 0.1 | μΑ |
| | I _{CEO} | $V_{CE} = -10V, I_B = 0$ | | | -100 | μΑ |
| Collector to base voltage | V _{CBO} | $I_{\rm C} = -10 \mu A, I_{\rm E} = 0$ | -60 | | | V |
| Collector to emitter voltage | V _{CEO} | $I_{C} = -100 \mu A, I_{B} = 0$ | -50 | | | V |
| Emitter to base voltage | V _{EBO} | $I_{\rm E} = -10 \mu A, \ I_{\rm C} = 0$ | _7 | | | V |
| Forward current transfer ratio | h _{FE} | $V_{CE} = -10V, I_C = -2mA$ | 180 | | 390 | |
| Collector to emitter saturation voltage | V _{CE(sat)} | $I_{\rm C} = -100 {\rm mA}, I_{\rm B} = -10 {\rm mA}$ | | - 0.3 | - 0.5 | V |
| Transition frequency | f _T | $V_{CB} = -10V, I_E = 1mA, f = 200MHz$ | | 80 | | MHz |
| Collector output capacitance | C _{ob} | $V_{CB} = -10V, I_E = 0, f = 1MHz$ | | 2.7 | | pF |





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